IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re l	Patent Application of)	
Shun	pei YAMAZAKI et al.)	ATTN: New Application
Based	d On: JP 2002-366158)	
Filed:	December 18, 2002)	
For:	METHOD FOR MANUFACTURING)	
	SEMICONDUCTOR APPARATUS, A	ND)	
	SEMICONDUCTOR APPARATUS A	ND)	
	ELECTRIC APPLIANCE)	

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56 and 37 C.F.R. 1.97-1.99, Applicant submits herewith a Form PTO-1449 listing references known to Applicant and requests that these references be made of record in the above identified application. Copies of the references listed are submitted herewith in accordance with 37 C.F.R. 1.98(a).

The Commissioner is hereby authorized to charge fees under 37 C.F.R. §§1.16, 1.17, 1.20(a), 1.20(b), 1.20(c), and 1.20(d) (except the Issue Fee) which may be required now or hereafter, or credit any overpayment to Deposit Account No. 50-2280. A duplicate copy of this sheet is attached.

Respectfully submitted,

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			TAITE	Application Number			
				Filing Date	December 8, 2003		
				First Named Inventor	Shunpei YAMAZAKI et al.		
(use as many sheets as necessary)				Group Art Unit			
				Examiner Name			
Sheet	1	of	1	Attorney Docket Number	0756-7225		

				U.S. PATENT DOCUMENT	ΓS	
Examiner Initials*	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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N. Hayasaka, "Recent Status of Thin Wafer Chip (die) Mounting," SEMICON JAI 2002, Dec. 5, 2002, pages 3-8								
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